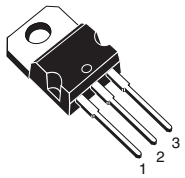
STP80NF12

N-channel 120V - 0.013Ω - 80A - TO-220
STripFET™ II Power MOSFET

General features

Type	V_{DSS} (@Tjmax)	$R_{DS(on)}$	I_D
STP80NF12	120V	<0.018Ω	80A (1)

- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization

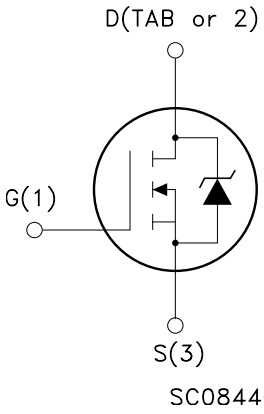


TO-220

Description

This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

Internal schematic diagram



Applications

- Switching application

Order codes

Part number	Marking	Package	Packaging
STP80NF12	P80NF12	TO-220	Tube

Contents

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		STB_P_W80NF12	STP80NF12FP	
V_{DS}	Drain-source voltage (V_{GS} = 0)	120		V
V_{DGR}	Drain-gate voltage (R_{GS} = 20KΩ)	120		V
V_{GS}	Gate-source voltage	± 22		V
I_D (1)	Drain current (continuous) at T_C = 25°C	80	11 (2)	A
I_D	Drain current (continuous) at T_C=100°C	60	60 (2)	A
I_{DM}(3)	Drain current (pulsed)	320	320 (2)	A
P_{TOT}	Total dissipation at T_C = 25°C	300	45	W
	Derating factor	2.0	0.3	W/°C
dv/dt(4)	Peak diode recovery voltage slope	10		V/ns
V_{ISO}	Insulation withstand voltage (DC)	--	2500	V
T_J T_{stg}	Operating junction temperature Storage temperature	-55 to 175		°C

1. Limited by Package
2. Limited only by maximum temperature allowed
3. Pulse width limited by safe operating area
4. Starting T_J = 25 °C, I_D = 40A, V_{DD} = 45V

Table 2. Thermal data

Symbol	Parameter	Value			Unit
		TO-247	D^2PAK TO-220	TO-220FP	
R_{thJC}	Thermal resistance junction-case Max	0.5	0.5	3.33	°C/W
R_{thJA}	Thermal resistance junction-ambient Max	50	62.5	62.5	°C/W
T_l	Maximum lead temperature for soldering purpose	300	300	300	°C

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 250µA, V_{GS}= 0	120			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = Max rating, V_{DS} = Max rating @125°C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±20V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250µA	2			V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS}= 10V, I_D= 40A		0.013	0.018	Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward transconductance	V_{DS} =15V, I_D = 40A		80		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} =25V, f=1 MHz, V_{GS}=0		4300 600 230		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 80V, I_D = 80A V_{GS} =10V		140 23 51	189	nC nC nC

1. Pulsed: pulse duration=300µs, duty cycle 1.5%

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD}= 50 V, I_D= 40A, R_G=4.7Ω, V_{GS}=10V *Figure 13 on page 8*		40 145 134 115		ns ns ns ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
I_{SD}	Source-drain current				80	A
I_{SDM}(1)	Source-drain current (pulsed)				320	A
V_{SD}(2)	Forward on voltage	I_{SD}=80A, V_{GS}=0			1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD}=80A, di/dt = 100A/µs, V_{DD}=35V, T_J = 150°C		155 0.85 11		ns µC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

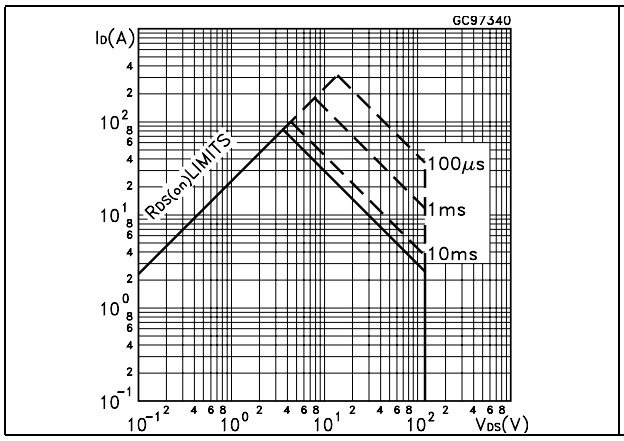


Figure 2. Thermal impedance

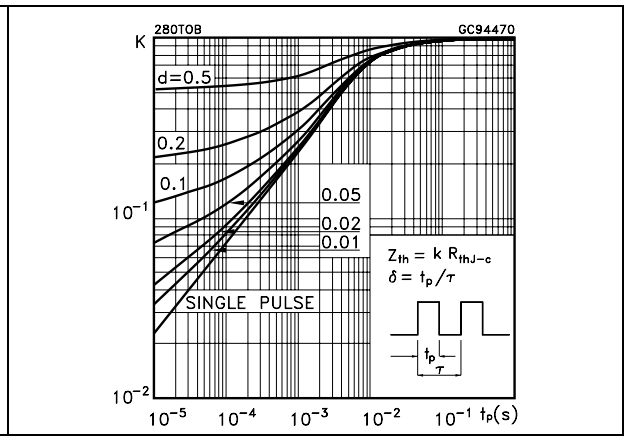


Figure 3. Output characteristics

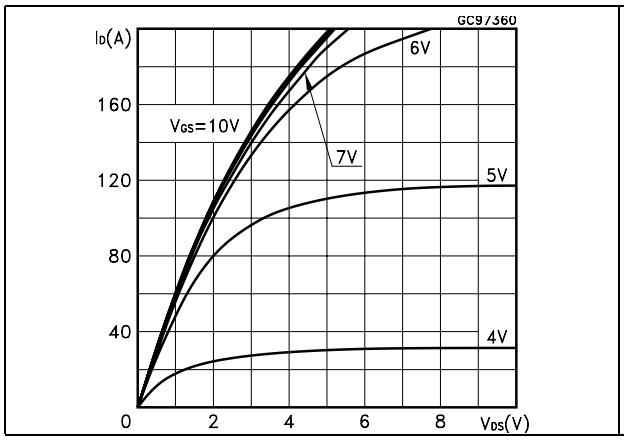


Figure 4. Transfer characteristics

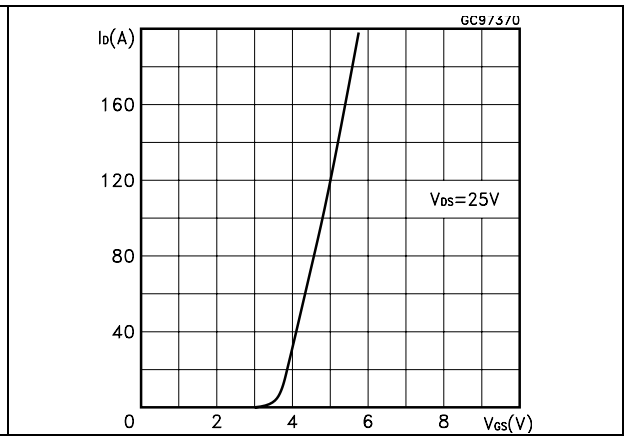


Figure 5. Transconductance

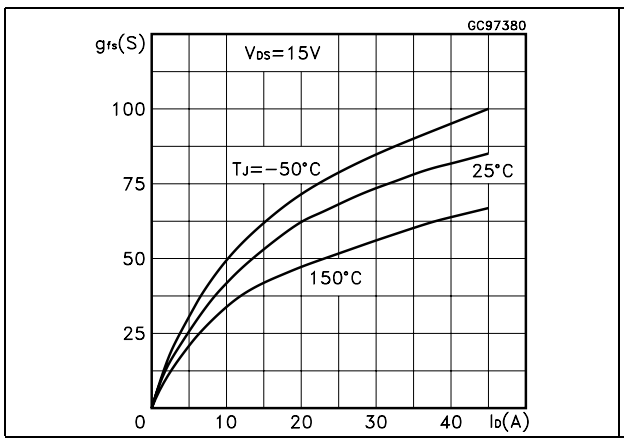


Figure 6. Static drain-source on resistance

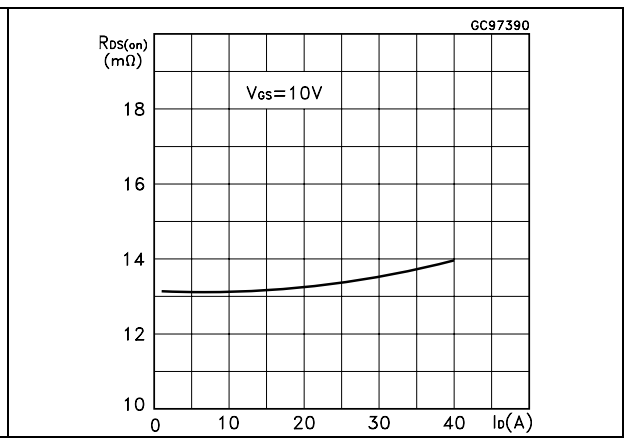


Figure 7. Gate charge vs. gate-source voltage

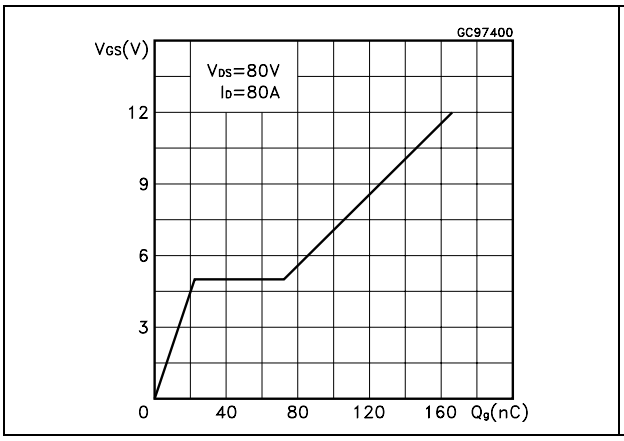


Figure 8. Capacitance variations

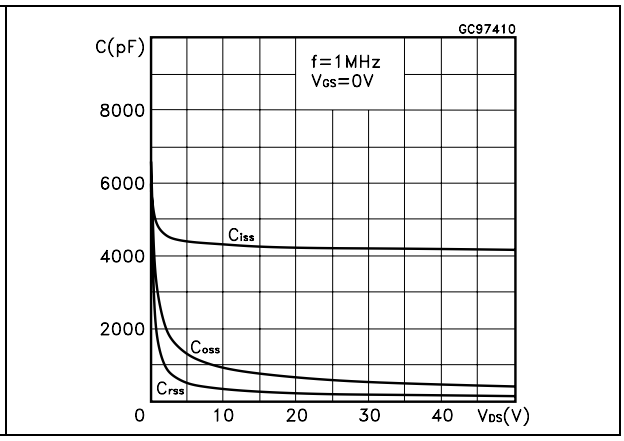


Figure 9. Normalized gate threshold voltage vs. temperature

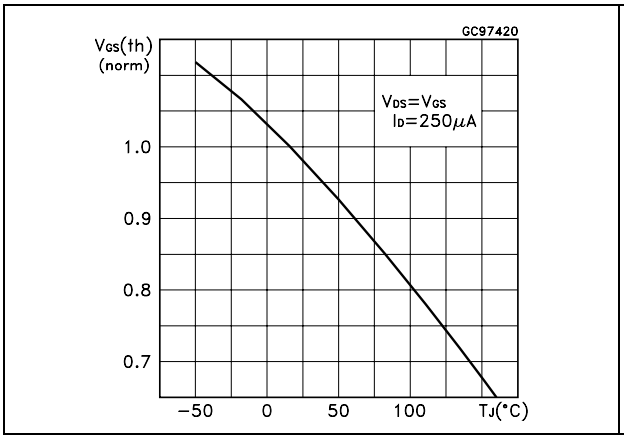


Figure 10. Normalized on resistance vs. temperature

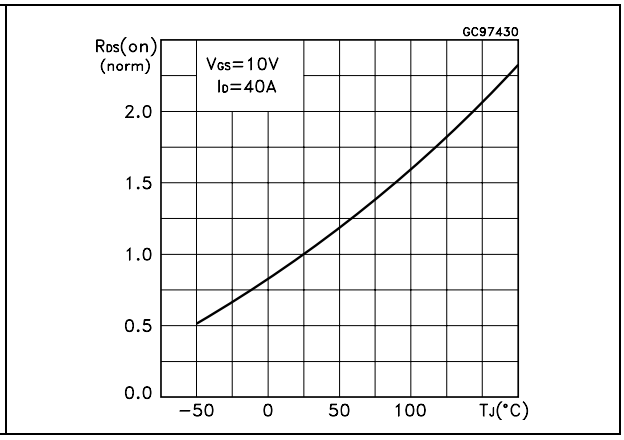


Figure 11. Source-drain diode forward characteristics

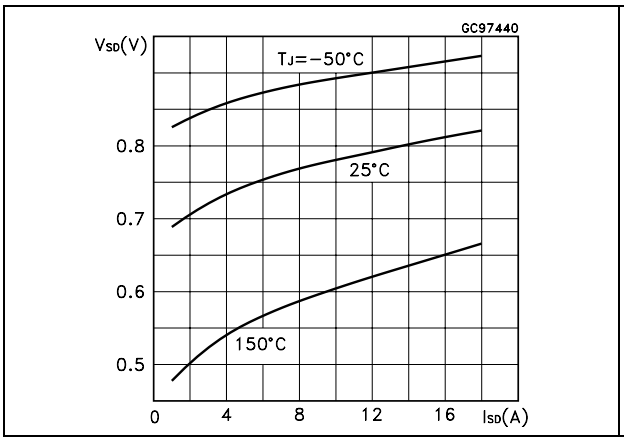
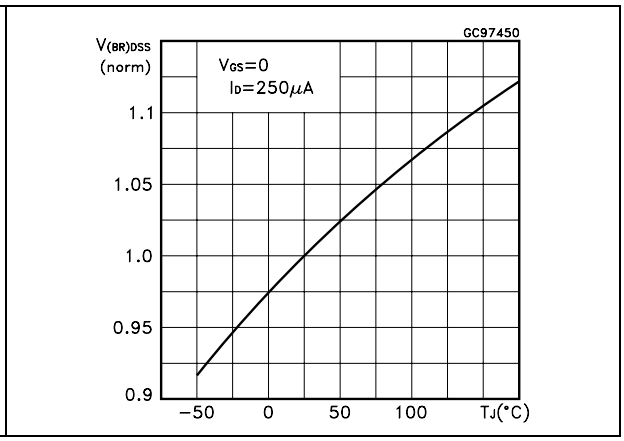


Figure 12. Normalized B_{VDSS} vs. temperature



3 Test circuit

Figure 13. Switching times test circuit for resistive load

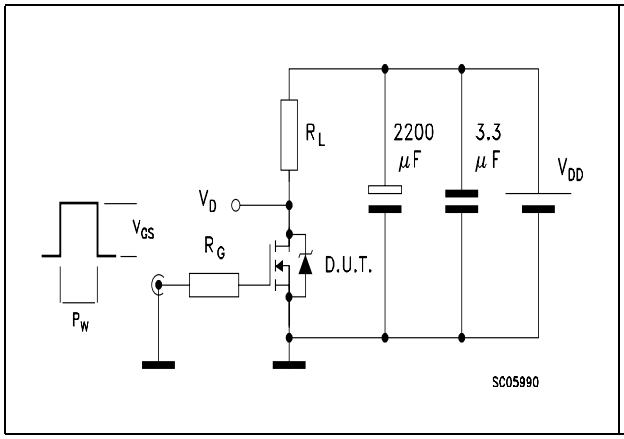


Figure 14. Gate charge test circuit

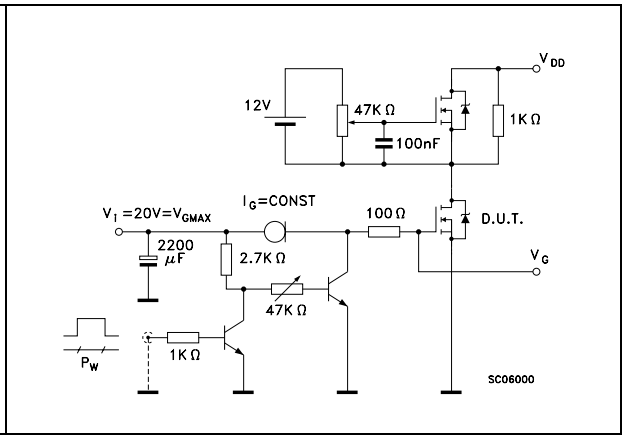


Figure 15. Test circuit for inductive load switching and diode recovery times

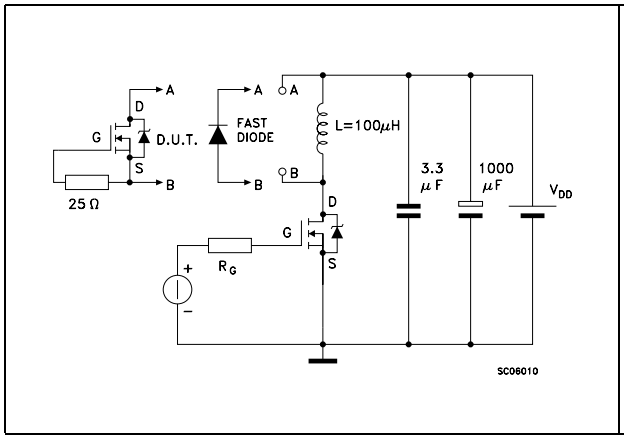


Figure 16. Unclamped Inductive load test circuit

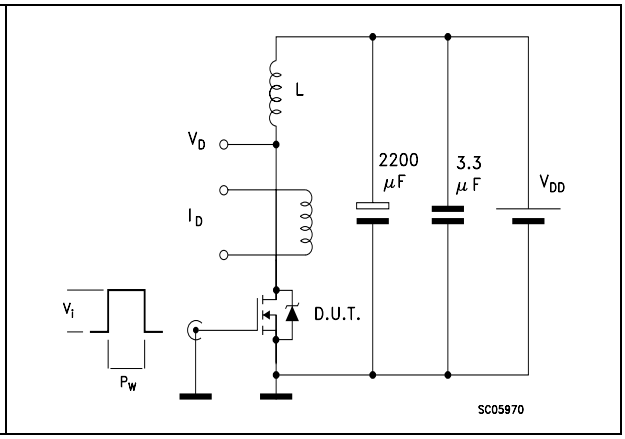
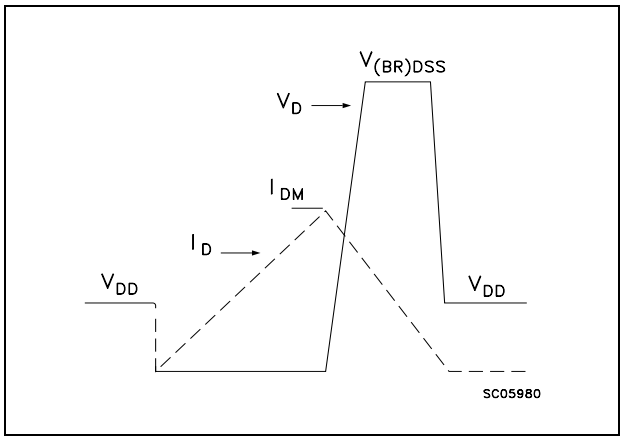


Figure 17. Unclamped inductive waveform

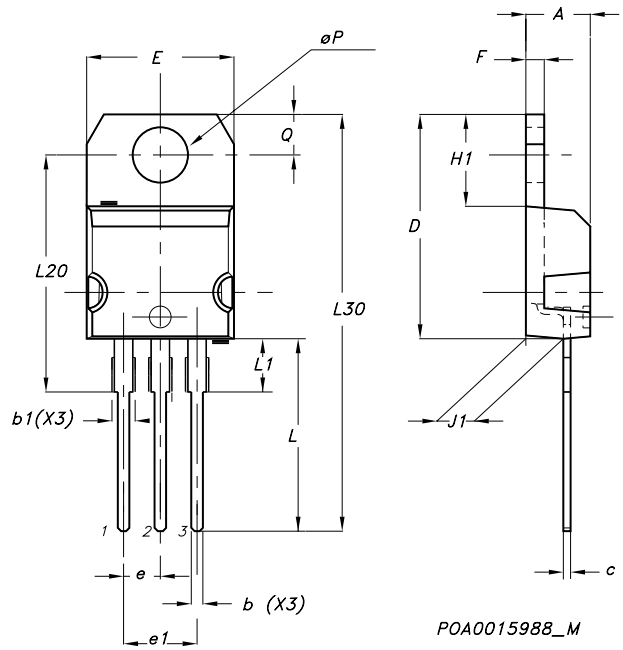


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-220 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



5 Revision history

Table 7. Revision history

Date	Revision	Changes
21-Jun-2004	2	Preliminary version
24-Jul-2006	3	The document has been reformatted, SOA updated
31-Jan-2007	4	Typo mistake on *Table 1*.

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